

STRUCTURE	Silicon monolithic integrated circuits
PRODUCT SERIES	Bipolar stepping motor driver
TYPE	<b>BD6425EFV</b>
FUNCTION	<ul style="list-style-type: none"> <li>• PWM constant current controllable two H bridge driver</li> <li>• Built-in translator circuit for CLK-IN control</li> <li>• Full, Half, and Quarter step modes</li> <li>• Mix decay control</li> </ul>

○Absolute maximum ratings(Ta=25°C)

Item	Symbol	Limit	Unit
Supply voltage	V <sub>CC1,2</sub>	-0.2~+45.0	V
Power dissipation	Pd	1.45 <sup>*1</sup>	W
		4.70 <sup>*2</sup>	W
Input voltage for control pin	V <sub>IN</sub>	-0.2~+5.5	V
RNF maximum voltage	V <sub>RNF</sub>	0.7	V
Maximum output current	I <sub>OUT</sub>	1.5 <sup>*3</sup>	A/phase
Operating temperature range	T <sub>opr</sub>	-25~+85	°C
Storage temperature range	T <sub>stg</sub>	-55~+150	°C
Junction temperature	T <sub>jmax</sub>	+150	°C

<sup>\*1</sup> 70mm×70mm×1.6mm glass epoxy board. Derating is done at 11.6mW/°C for operating above Ta=25°C.

<sup>\*2</sup> 4-layer recommended board. Derating is done at 37.6mW/°C for operating above Ta=25°C.

<sup>\*3</sup> Do not, however exceed Pd, ASO and T<sub>jmax</sub>=150°C.

○Recommended operating conditions (Ta=-25~+85°C)

Item	Symbol	Min.	Typ.	Max.	Unit
Supply voltage	V <sub>CC1,2</sub>	19	37	42	V
Output current	I <sub>OUT</sub>	-	1.0	1.2 <sup>*4</sup>	A/phase

<sup>\*4</sup> Do not, however exceed Pd, ASO.

This product isn't designed for protection against radioactive rays.

Status of this document

The Japanese version of this document is the formal specification.

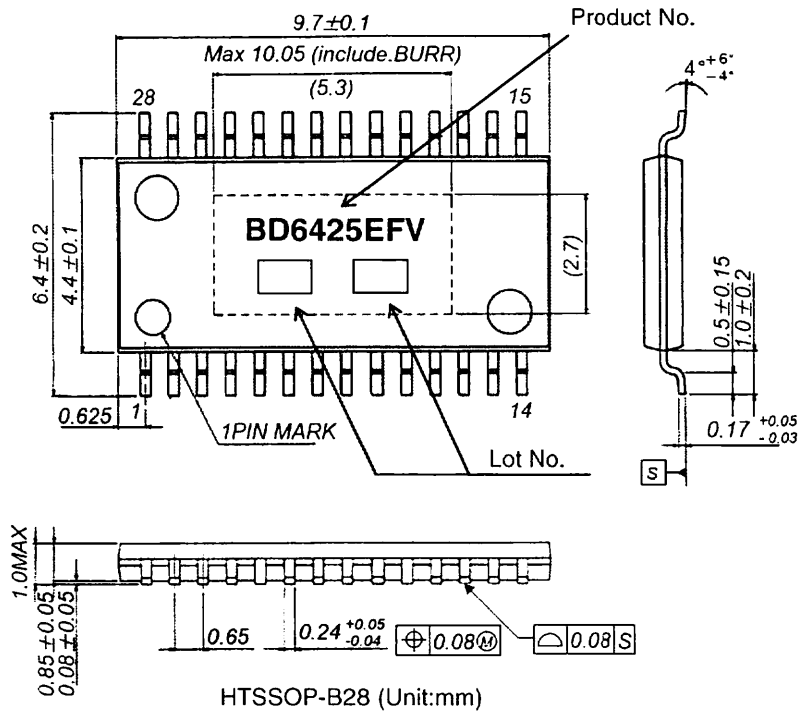
A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document, formal version takes priority.

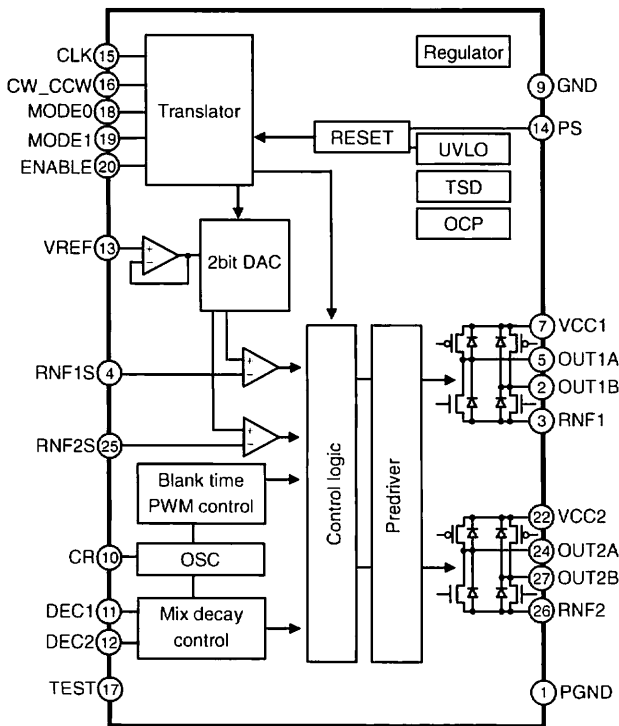
○Electrical characteristics (Unless otherwise specified Ta=25°C, V<sub>CC1,2</sub>=37V)

Item	Symbol	Limit			Unit	Conditions
		Min.	Typ.	Max.		
<b>Whole</b>						
Circuit current at standby	I <sub>CCST</sub>	-	1.0	2.5	mA	PS=L
Circuit current	I <sub>CC</sub>	-	2.0	5.0	mA	PS=H, VREF=3V
<b>Control input (CLK, CW_CCW, MODE0, MODE1, ENABLE, DEC1, DEC2, PS)</b>						
H level input voltage	V <sub>INH</sub>	2.0	-	-	V	
L level input voltage	V <sub>INL</sub>	-	-	0.8	V	
H level input current	I <sub>INH</sub>	35	50	100	μA	V <sub>IN</sub> =5V
L level input current	I <sub>INL</sub>	-10	0	-	μA	V <sub>IN</sub> =0V
<b>Output (OUT1A, OUT1B, OUT2A, OUT2B)</b>						
Output ON resistance	R <sub>ON</sub>	-	1.10	1.43	Ω	I <sub>OUT</sub> =1.0A, Sum of upper and lower
Output leak current	I <sub>LEAK</sub>	-	-	10	μA	
<b>Current control</b>						
RNFXS input current	I <sub>RNFS</sub>	-2.0	-0.1	-	μA	RNFXS=0V
RNFX input current	I <sub>RNF</sub>	-40	-20	-	μA	RNFX=0V
VREF input current	I <sub>VREF</sub>	-2.0	-0.1	-	μA	VREF=0V
VREF input voltage range	V <sub>REF</sub>	0	-	3.0	V	
Comparator threshold	V <sub>CTH</sub>	0.57	0.60	0.63	V	VREF=3V
Minimum on time (Blank time)	t <sub>ONMIN</sub>	0.5	1.5	3.0	μs	C=470pF, R=82kΩ

○Package outline



○Block diagram



○Pin No. / Pin name

Pin No.	Pin name	Pin No.	Pin name
1	GND	15	CLK
2	OUT1B	16	CW_CCW
3	RNF1	17	TEST
4	RNF1S	18	MODE0
5	OUT1A	19	MODE1
6	NC	20	ENABLE
7	VCC1	21	NC
8	NC	22	VCC2
9	GND	23	NC
10	CR	24	OUT2A
11	DEC1	25	RNF2S
12	DEC2	26	RNF2
13	VREF	27	OUT2B
14	PS	28	NC

NC : Non Connection

## ○Operation Notes

- (1) Absolute maximum ratings  
An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.
- (2) Power supply lines  
As return of current regenerated by back EMF of motor happens, take steps such as putting capacitor between power supply and GND as an electric pathway for the regenerated current. Be sure that there is no problem with each property such as emptied capacity at lower temperature regarding electrolytic capacitor to decide capacity value. If the connected power supply does not have sufficient current absorption capacity, regenerative current will cause the voltage on the power supply line to rise, which combined with the product and its peripheral circuitry may exceed the absolute maximum ratings. It is recommended to implement a physical safety measure such as the insertion of a voltage clamp diode between the power supply and GND pins.
- (3) GND potential  
The potential of GND pin must be minimum potential in all operating conditions.
- (4) Metal on the backside (Define the side where product markings are printed as front)  
The metal on the backside is shorted with the backside of IC chip therefore it should be connected to GND. Be aware that there is a possibility of malfunction or destruction if it is shorted with any potential other than GND.
- (5) Thermal design  
Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions. This IC exposes its frame of the backside of package. Note that this part is assumed to use after providing heat dissipation treatment to improve heat dissipation efficiency . Try to occupy as wide as possible with heat dissipation pattern not only on the board surface but also the backside.
- (6) Actions in strong electromagnetic field  
Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.
- (7) ASO  
When using the IC, set the output transistor so that it does not exceed absolute maximum ratings or ASO.
- (8) Thermal shutdown circuit  
The IC has a built-in thermal shutdown circuit (TSD circuit). If the chip temperature becomes  $T_{jmax}=150^{\circ}\text{C}$ , and higher, coil output to the motor will be open. The TSD circuit is designed only to shut the IC off to prevent runaway thermal operation. It is not designed to protect or indemnify peripheral equipment. Do not use the TSD function to protect peripheral equipment.
- (9) Ground Wiring Pattern  
When using both large current and small signal GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.
- (10) TEST pin  
Be sure to connect TEST pin to GND.

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